

PS2503-1, PS2503L-1

R08DS0204EJ0100

Rev.1.00

Dec 25, 2020

LOW INPUT CURRENT, HIGH SPEED SWITCHING

DESCRIPTION

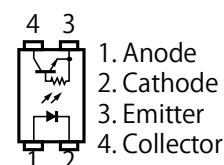
The PS2503-1 and PS2503L-1 are optically coupled isolator containing a GaAs light emitting diode and an NPN silicon phototransistor.

The PS2503-1 is in a plastic DIP (Dual In-line Package) and the PS2503L-1 is lead bending type (Gull-wing) for surface mount.

FEATURES

- High isolation voltage ($BV = 5\,000\text{ Vr.m.s.}$)
- High-speed switching ($t_r = 20\ \mu\text{s TYP.}$, $t_f = 30\ \mu\text{s TYP.}$)
- Ordering number of taping product: PS2503L-1-F3 : 2 000 pcs/reel
- Pb-Free product
- Safety standards
 - UL approved: UL1577, Double protection
 - CSA approved: CAN/CSA-C22.2 No. 62368-1, Reinforced insulation

PIN CONNECTION (Top View)

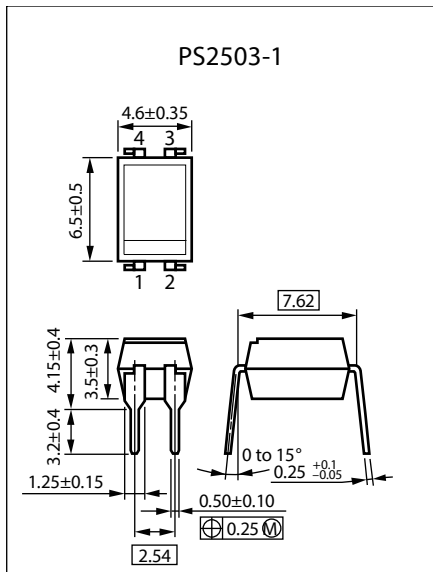


APPLICATIONS

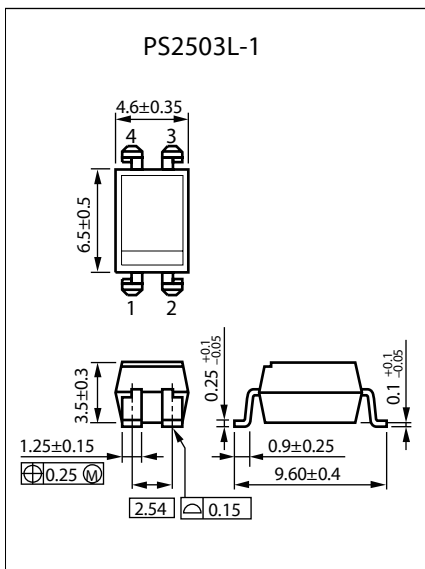
- Measurement equipment
- Programmable logic controller
- Telephone/Telegraph Receiver
- Power supply

PACKAGE DIMENSIONS (UNIT: mm)

DIP Type



Lead Bending Type For Surface Mount

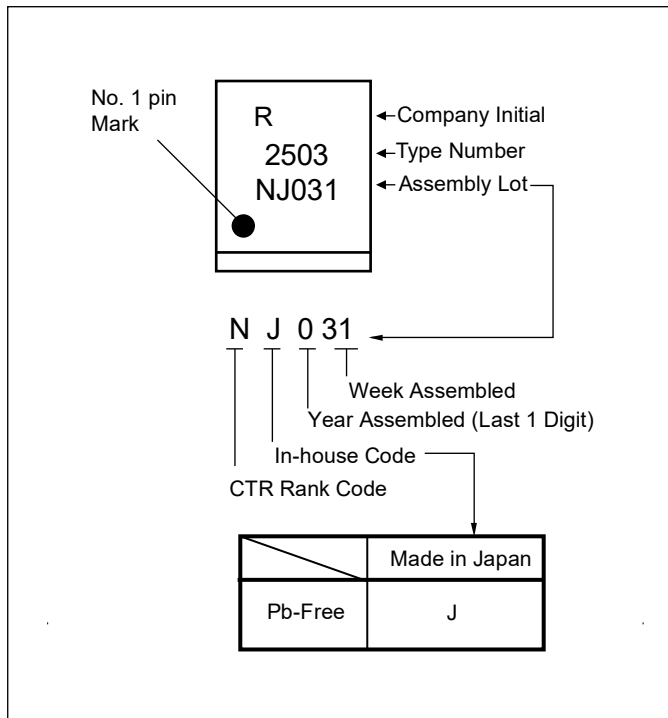


Weight (4-pin DIP) : 0.26 g (typ.)

PHOTOCOUPLER CONSTRUCTION

Parameter	PS2503-1, PS2503L-1
Air Distance (MIN.)	7 mm
Creepage Distance (MIN.)	7 mm
Isolation Distance (MIN.)	0.3 mm

MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number *1	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number *2
PS2503-1	PS2503-1-A	Pb-Free	Magazine case 100 pcs	Standard products (UL, CSA approved)	PS2503-1
PS2503L-1	PS2503L-1-A				PS2503L-1
PS2503L-1-F3	PS2503L-1-F3-A		Embossed Tape 2 000 pcs/reel		PS2503L-1

Notes: *1. When specifying CTR rank, please add "/CTR rank" after Order Number.

ex. L rank : PS2503-1-A/L

Notes: *2. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Reverse Voltage	V_R	6	V
	Forward Current (DC)	I_F	80	mA
	Power Dissipation Derating	$\Delta P_D/^{\circ}\text{C}$	1.5	mW/ $^{\circ}\text{C}$
	Power Dissipation	P_D	150	mW
	Peak Forward Current*1	I_{FP}	1	A
Transistor	Collector to Emitter Voltage	V_{CEO}	40	V
	Emitter to Collector Voltage	V_{ECO}	0.6	V
	Collector Current	I_C	30	mA
	Power Dissipation Derating	$\Delta P_C/^{\circ}\text{C}$	1.5	mW/ $^{\circ}\text{C}$
	Power Dissipation	P_C	150	mW
Isolation Voltage*2		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T_A	-55 to +100	$^{\circ}\text{C}$
Storage Temperature		T_{stg}	-55 to +150	$^{\circ}\text{C}$

Note: *1. PW = 100 μs , Duty Cycle = 1 %

*2. AC voltage for 1 minute at $T_A = 25\text{ }^{\circ}\text{C}$, RH = 60 % between input and output.

Pins 1-2 shorted together, 3-4 shorted together.

ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = 1\text{ mA}$		1.1	1.3	V
	Reverse Current	I_R	$V_R = 5\text{ V}$			5	
	Terminal Capacitance	C_t	$V = 0\text{ V}, f = 1.0\text{ MHz}$		50		pF
Transistor	Collector to Emitter Dark Current	I_{CEO}	$V_{CE} = 40\text{ V}, I_F = 0\text{ mA}$			100	nA
Coupled	Current Transfer Ratio (I_C/I_F)	CTR	$I_F = 1\text{ mA}, V_{CE} = 5\text{ V}$	100	200	400	%
	Collector Saturation Voltage	$V_{CE(sat)}$	$I_F = 1\text{ mA}, I_C = 0.2\text{ mA}$			0.25	V
	Isolation Resistance	R_{I-O}	$V_{I-O} = 1.0\text{ kV}_{DC}$	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	$V = 0\text{ V}, f = 1.0\text{ MHz}$		0.5		pF
	Rise Time*2	t_r	$V_{CC} = 5\text{ V}, I_F = 1\text{ mA}, R_L = 10\text{ k}\Omega$		20		μs
	Fall Time*2	t_f			20		

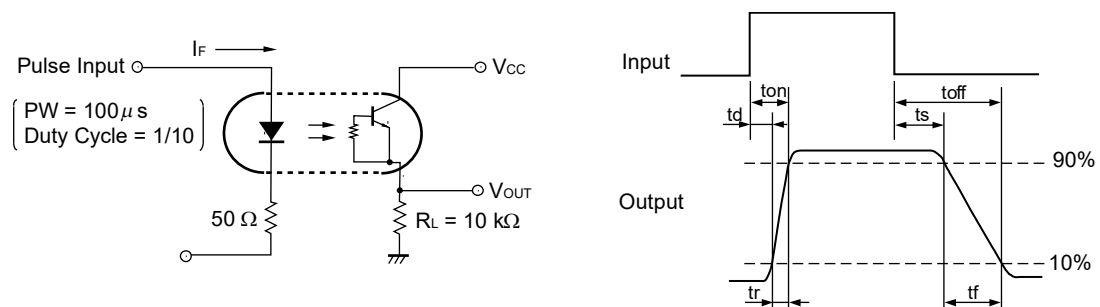
Note: *1. CTR rank

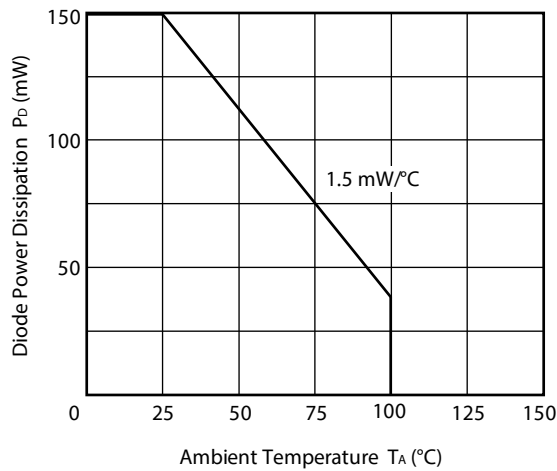
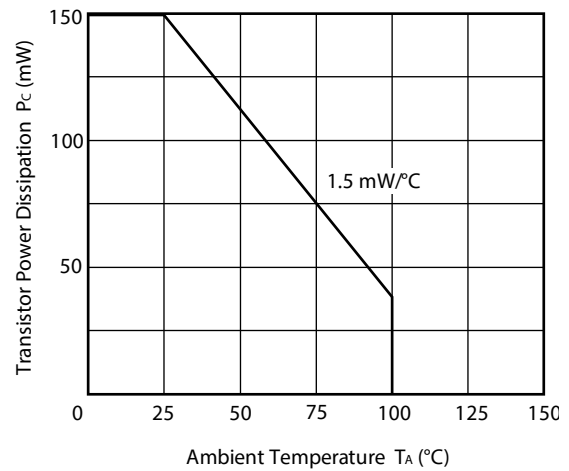
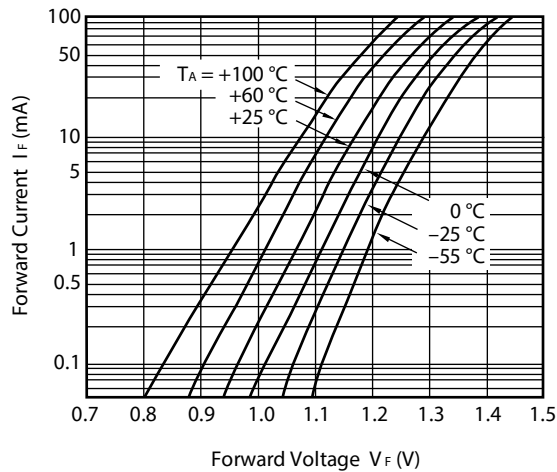
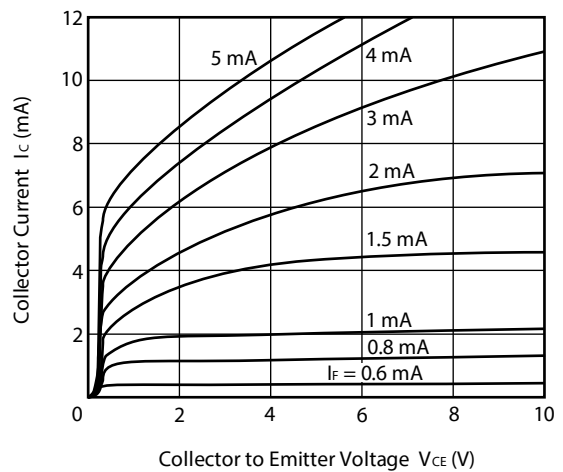
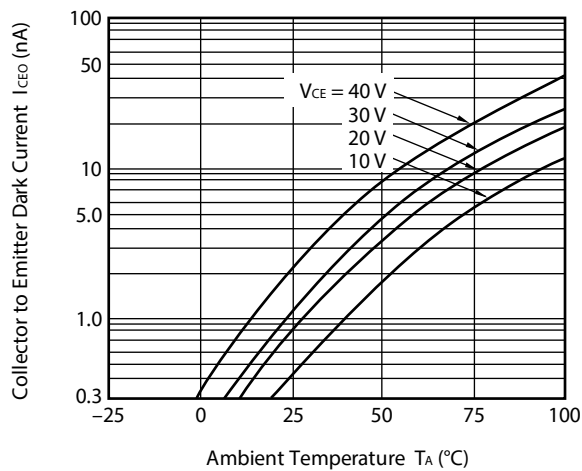
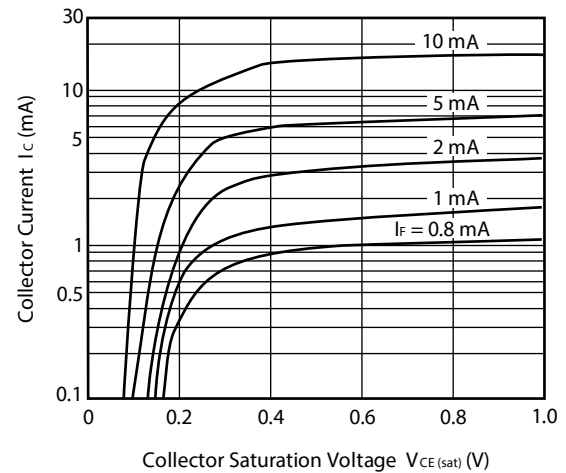
K : 200 to 400 (%)

L : 150 to 300 (%)

M : 100 to 200 (%)

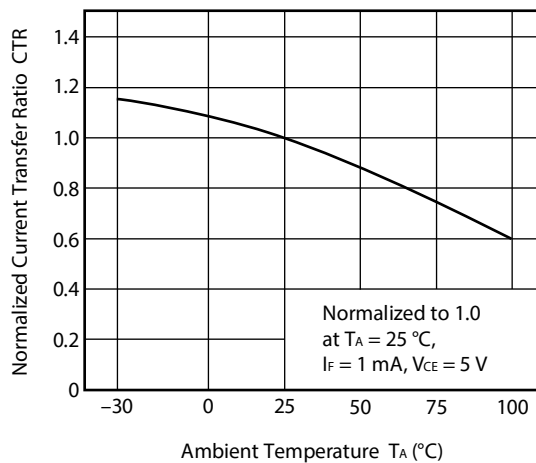
*2. Test Circuit for Switching Time



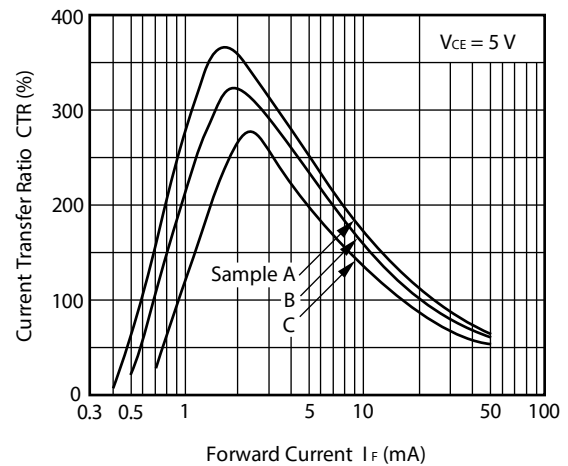
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)
**DIODE POWER DISSIPATION vs.
AMBIENT TEMPERATURE**

**TRANSISTOR POWER DISSIPATION
vs. AMBIENT TEMPERATURE**

**FORWARD CURRENT vs.
FORWARD VOLTAGE**

**COLLECTOR CURRENT vs.
COLLECTOR TO EMITTER VOLTAGE**

**COLLECTOR TO EMITTER DARK
CURRENT vs. AMBIENT TEMPERATURE**

**COLLECTOR CURRENT vs.
COLLECTOR SATURATION VOLTAGE**


Remark The graphs indicate nominal characteristics.

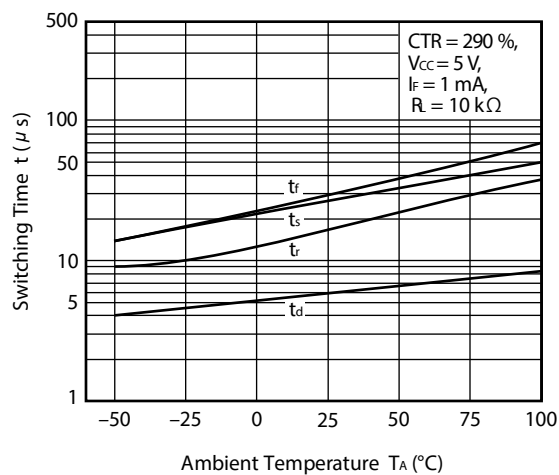
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



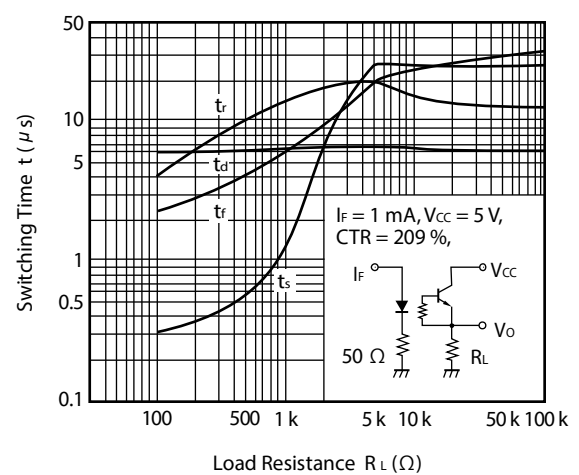
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



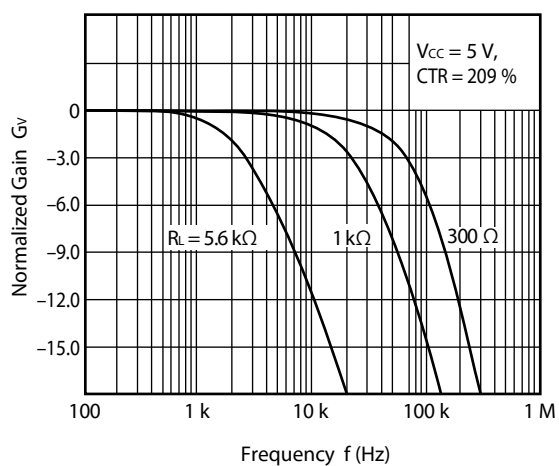
SWITCHING TIME vs. AMBIENT TEMPERATURE



SWITCHING TIME vs. LOAD RESISTANCE



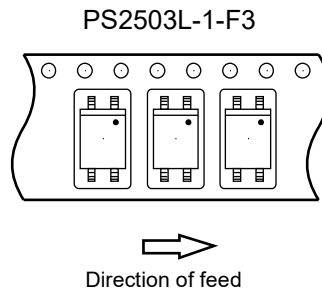
FREQUENCY RESPONSE



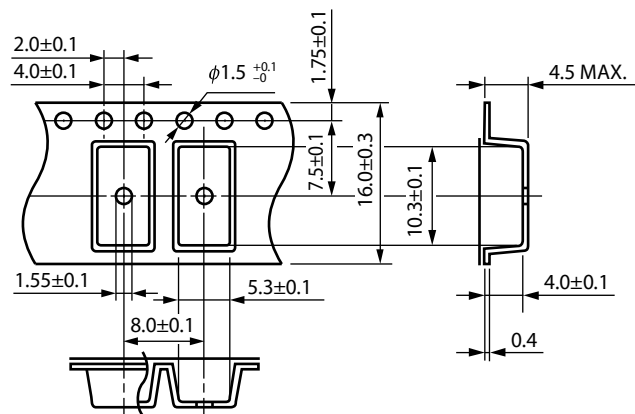
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

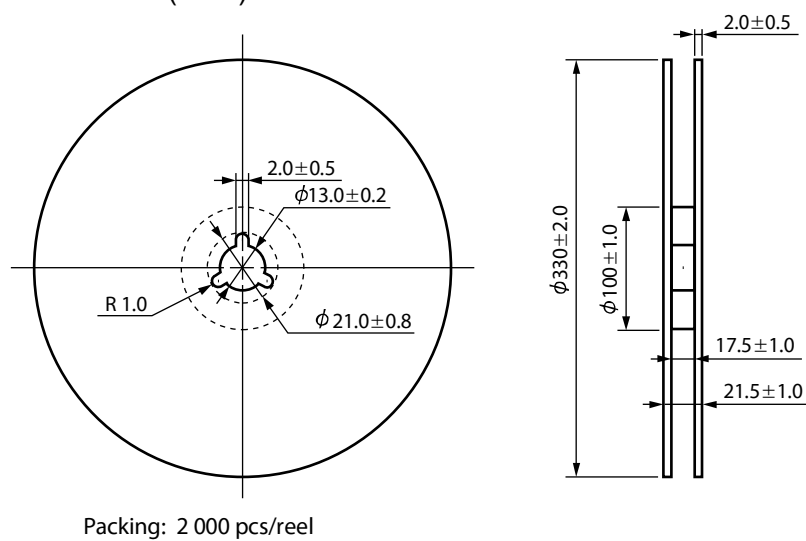
Taping Direction



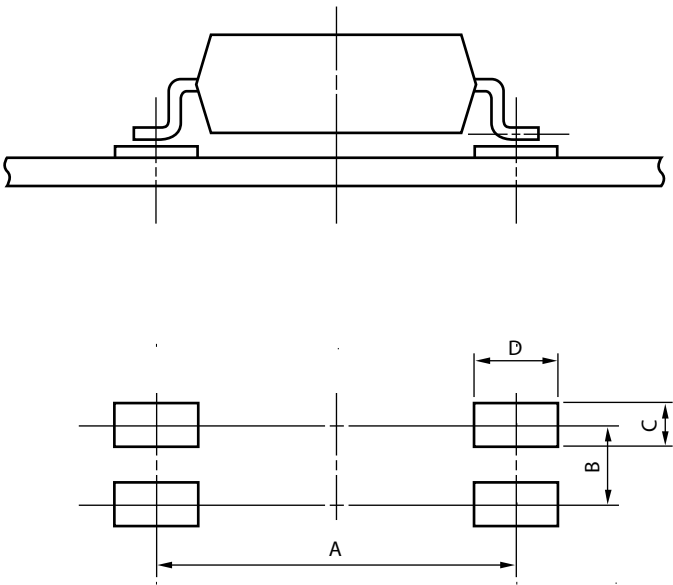
Outline and Dimensions (Tape)



Outline and Dimensions (Reel)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Part Number	Lead Bending	A	B	C	D
PS2503L	Lead Bending Type For Surface Mount	8.2	2.54	1.7	2.2

Remark All dimensions in this figure must be evaluated before use.

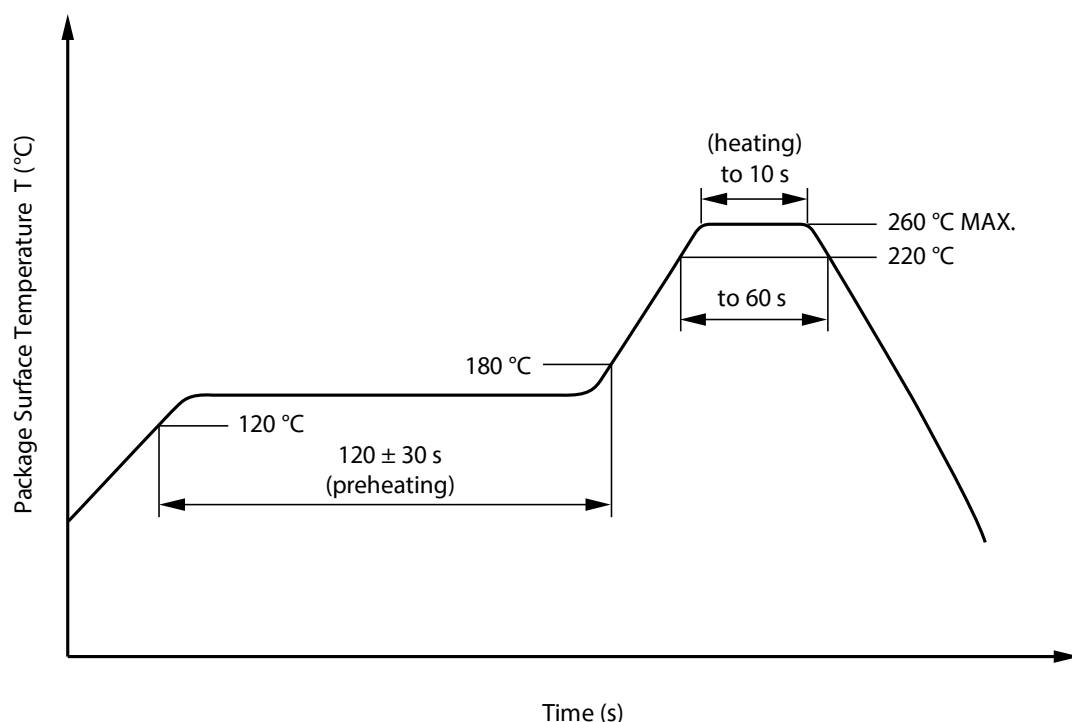
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

• Peak reflow temperature	260 °C or below (package surface temperature)
• Time of peak reflow temperature	10 seconds or less
• Time of temperature higher than 220°C	60 seconds or less
• Time to preheat temperature from 120 to 180°C	120 ± 30 s
• Number of reflows	Three
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

• Temperature	260 °C or below (molten solder temperature)
• Time	10 seconds or less
• Preheating conditions	120 °C or below (package surface temperature)
• Number of times	One (Allowed to be dipped in solder including plastic mold portion.)
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

• Peak Temperature (lead part temperature)	350 °C or below
• Time (each pins)	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(b) Please be sure that the temperature of the package would not be heated over 100 °C

(4) Cautions

- Flux Cleaning
Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
- Do not use fixing agents or coatings containing halogen-based substances.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.
3. Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
4. Do not use fixing agents or coatings containing halogen-based substances.

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

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